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(54) Title: MIXED CONDUCTING VOLATILE MEMORY ELEMENT FOR ACCELERATED WRITING OF NONVOLATILE MEMRISTIVE DEVICE

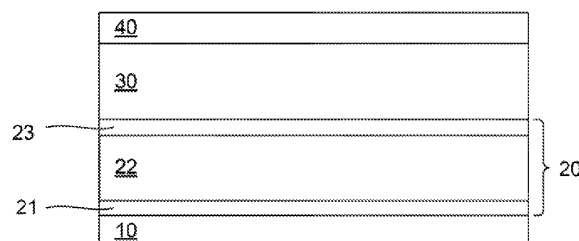


FIG. 2

(57) Abstract: An analog memory structure, and methods of writing to such a structure are provided. The analog memory structure includes a volatile memory element in series with a non-volatile memory element. The analog memory structure may change resistance upon application of a voltage. This may enable accelerated writing of the analog memory structure.



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